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# United States Patent [19]

**Acciaioli et al.**

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[54] **LID FOR A MICROELECTRONIC PACKAGE**

[75] Inventors: **John V. Acciaioli**, Tucson, Ariz.; **Myra M. Boenke**, Hopewell Junction; **Larry D. Gross**, Poughkeepsie, both of N.Y.; **Martin Marotti**, Carmel, Ind.; **John B. Pavelka**, Austin, Tex.; **Roland N. Zapfe**, Rochester, Minn.

[73] Assignee: **International Business Machines Corporation**, Armonk, N.Y.

[**] Term: **14 Years**

[21] Appl. No.: **61,550**

[22] Filed: **Oct. 24, 1996**

[51] **LOC (6) Cl.** .......................................................... **13-02**

[52] **U.S. Cl.** .............................................................. **D13/182**

[58] **Field of Search** ................................ D13/182; 361/1, 361/56, 139, 600, 627, 679

[56] **References Cited**

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*Primary Examiner*—Brian N. Vinson
*Attorney, Agent, or Firm*—Steven J. Soucar

[57] **CLAIM**

We claim the ornamental design for a lid for a microelectronic package, as shown and described.

## DESCRIPTION

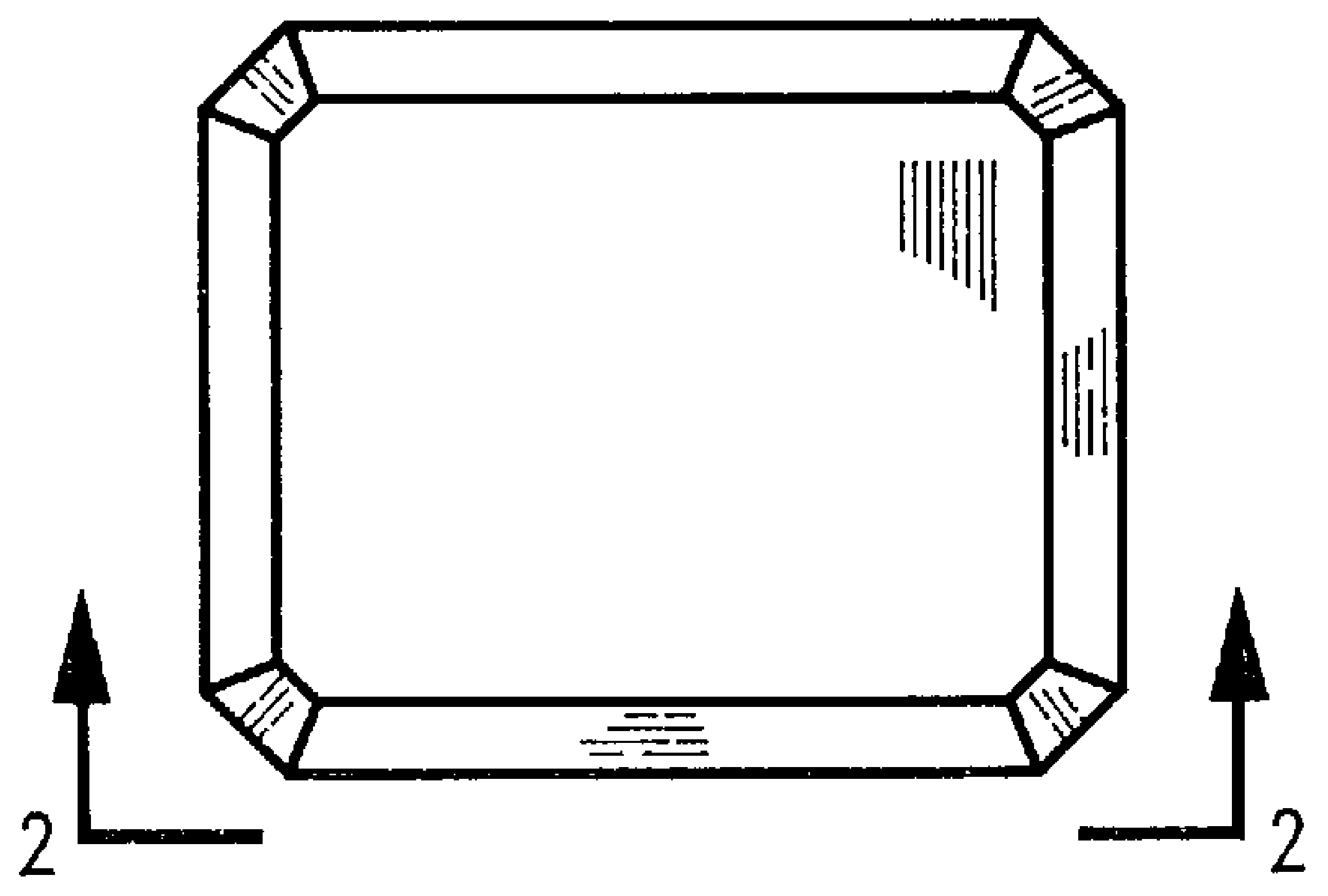
FIG. **1** is a top plan view of a lid for a microelectronic package showing a first embodiment of my new design;

FIG. **2** is a side elevational view thereof, the opposite side being identical in appearance;

FIG. **3** is a bottom plan view thereof; and,

FIG. **4** is a bottom plan view of a lid for a microelectronic package showing a second embodiment of my new design, the only difference from the first embodiment residing in the appearance of the bottom.

**1 Claim, 1 Drawing Sheet**



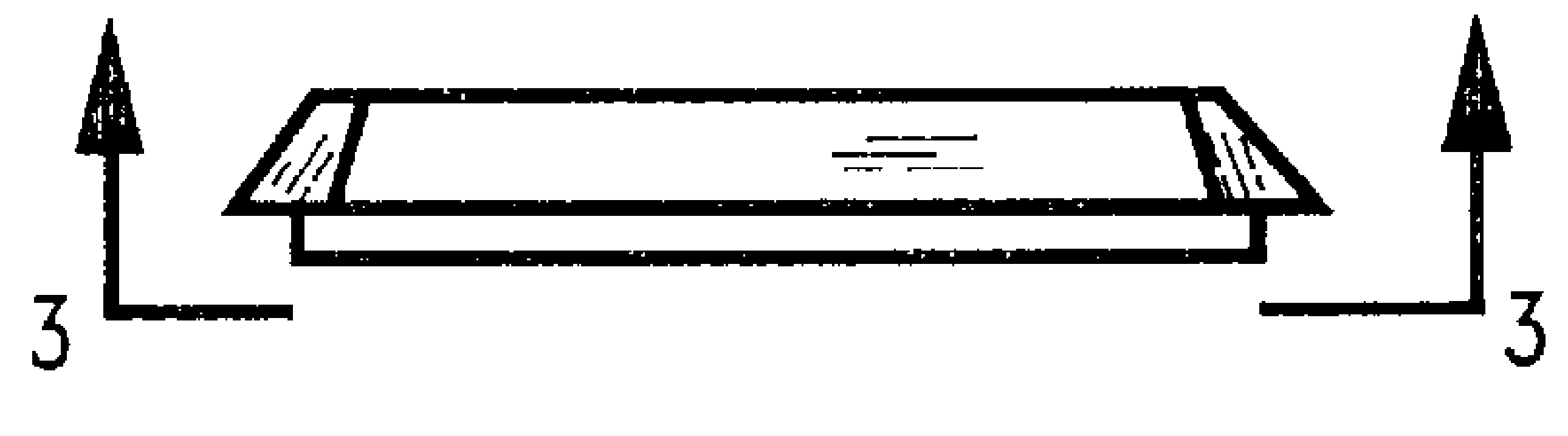


FIG. 1

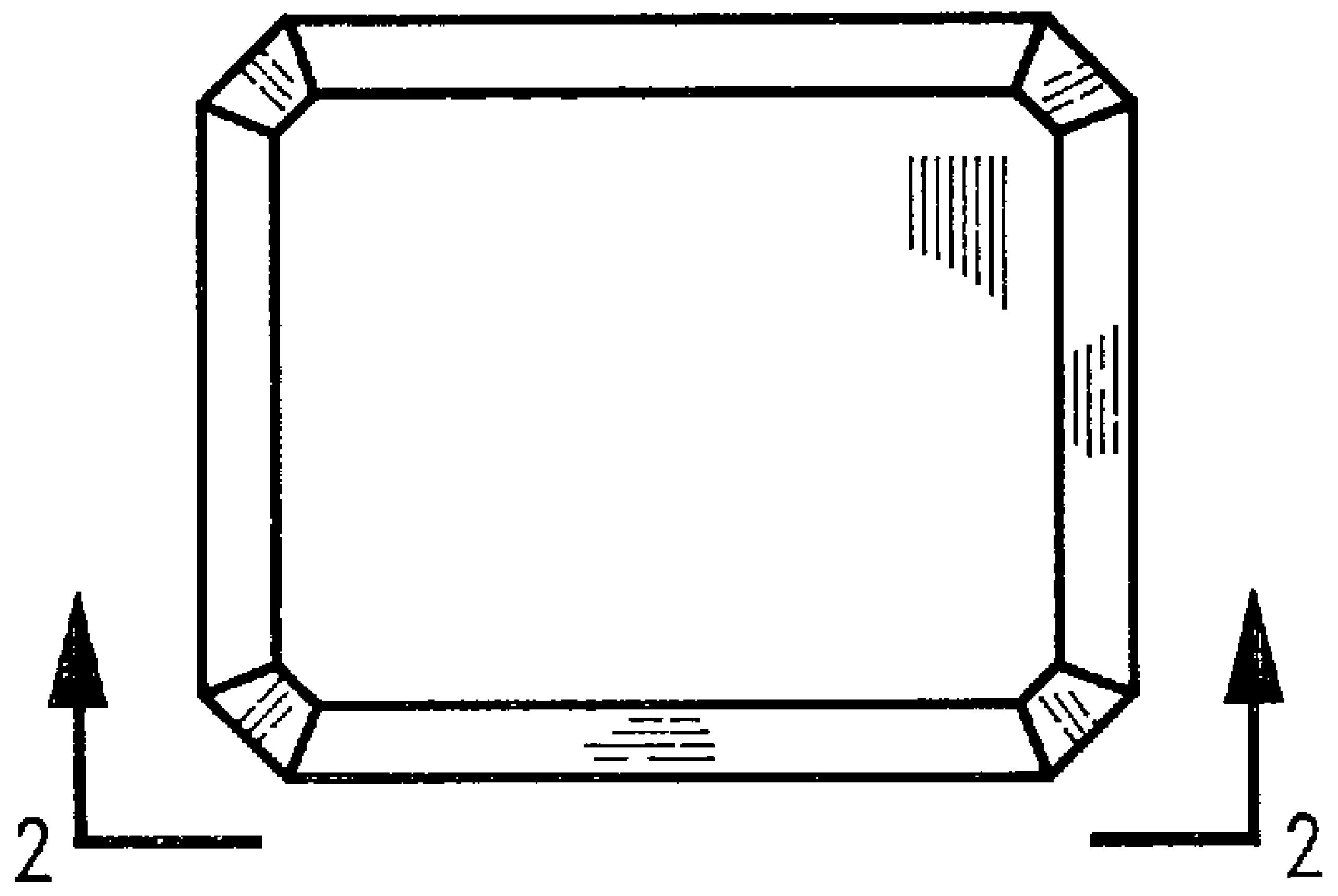


FIG. 2

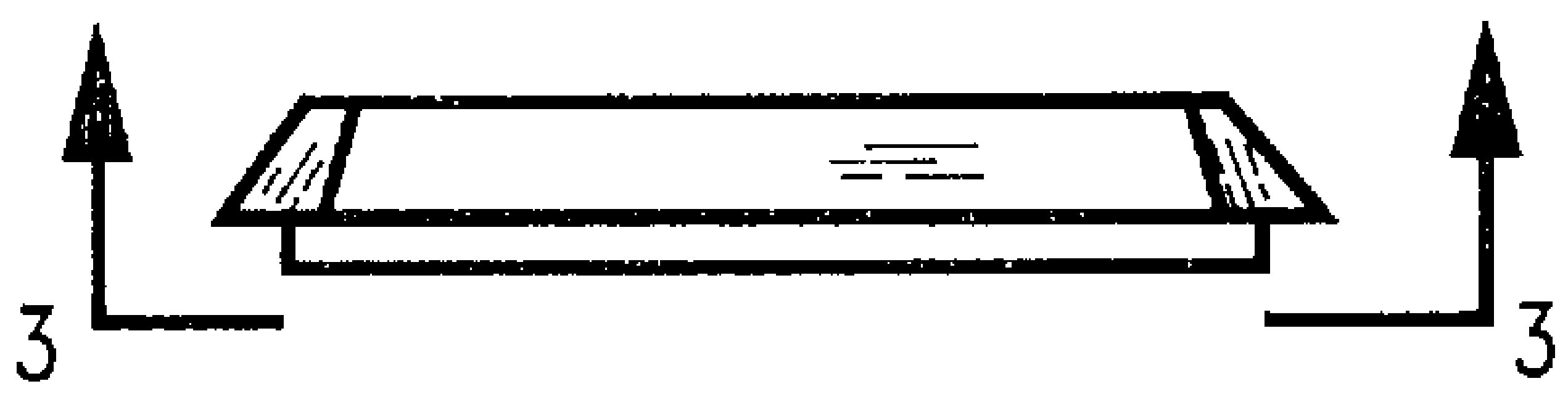


FIG. 3

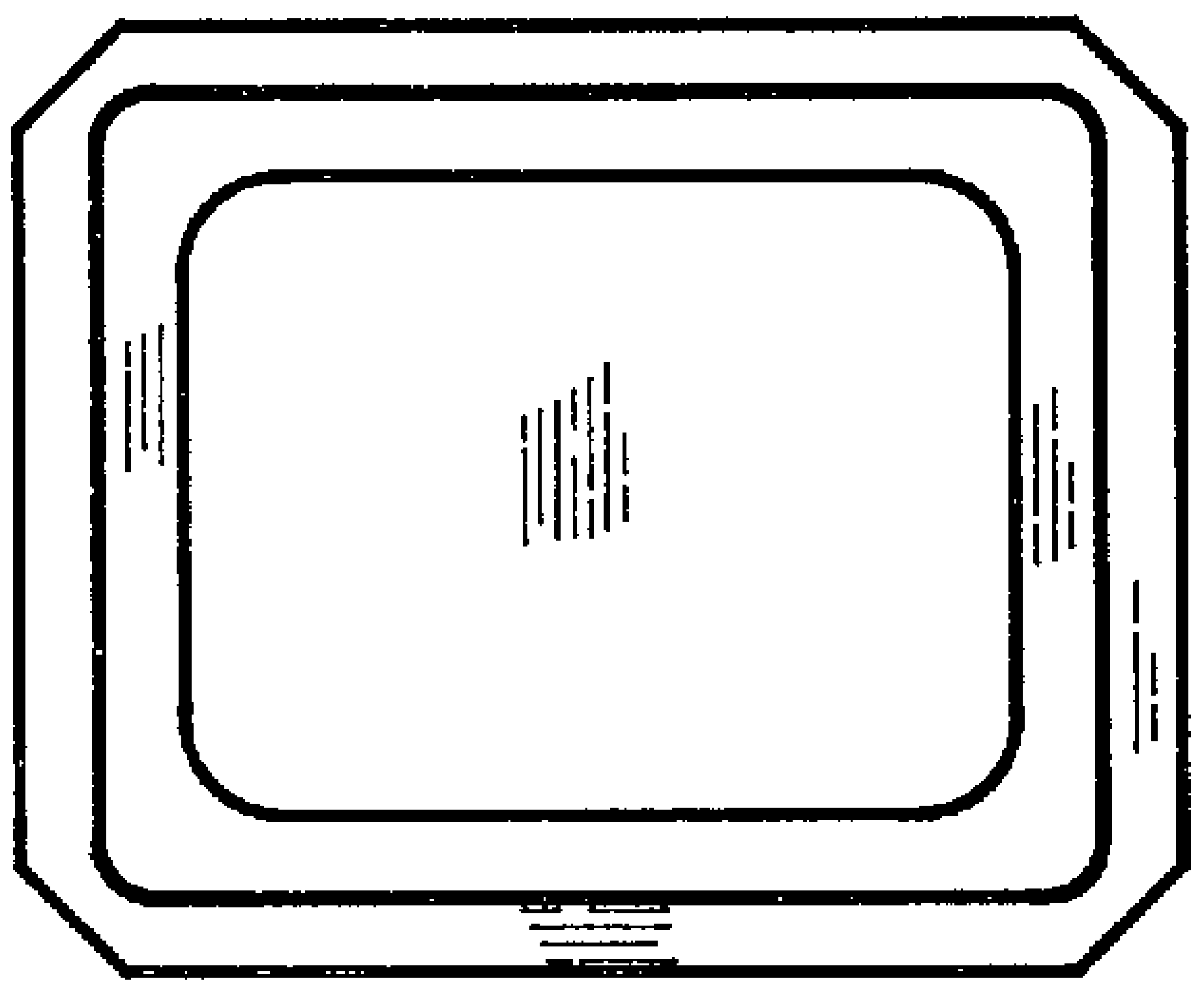


FIG. 4